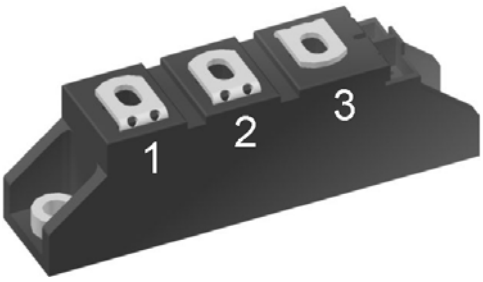
Standard Rectifier Module

V_{RRM} = 2x 1600 V
I_{FAV} = 99 A
V_F = 1.22 V

Phase leg

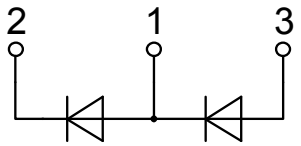
Part number

MDD72-16N1B



Backside: isolated

E72873



Features / Advantages:

- Package with DCB ceramic
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current

Applications:

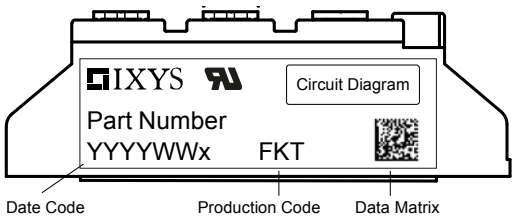
- Diode for main rectification
- For single and three phase bridge configurations
- Supplies for DC power equipment
- Input rectifiers for PWM inverter
- Battery DC power supplies
- Field supply for DC motors

Package: TO-240AA

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RSM}	*max. non-repetitive reverse blocking voltage*		T_{VJ} = 25°C			1700	V
V_{RRM}	*max. repetitive reverse blocking voltage*		T_{VJ} = 25°C			1600	V
I_R	*reverse current*	V_R = 1600 V	T_{VJ} = 25°C			200	µA
		V_R = 1600 V	T_{VJ} = 150°C			15	mA
V_F	*forward voltage drop*	I_F = 150 A	T_{VJ} = 25°C			1.27	V
		I_F = 300 A				1.60	V
		I_F = 150 A	T_{VJ} = 125 °C			1.22	V
		I_F = 300 A				1.60	V
I_{FAV}	*average forward current*	T_C = 100°C	T_{VJ} = 150°C			99	A
$I_{F(RMS)}$	*RMS forward current*	180° sine				180	A
V_{F0}	*threshold voltage* } *for power loss calculation only*		T_{VJ} = 150°C			0.80	V
r_F	*slope resistance* }					2.3	mΩ
R_{thJC}	*thermal resistance junction to case*					0.35	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.20		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			357	W
I_{FSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			1.70	kA
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			1.84	kA
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			1.45	kA
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			1.56	kA
I^2t	*value for fusing*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			14.5	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			14.0	kA²s
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			10.4	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			10.1	kA²s
C_J	*junction capacitance*	V_R = 400 V; f = 1 MHz	T_{VJ} = 25°C		116		pF

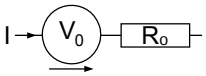
Package TO-240AA					Ratings			
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I_{RMS}	*RMS current*	per terminal					200	A
T_{VJ}	*virtual junction temperature*				-40		150	°C
T_{op}	*operation temperature*				-40		125	°C
T_{stg}	*storage temperature*				-40		125	°C
Weight						90		g
M_D	*mounting torque*				2.5		4	Nm
M_T	*terminal torque*				2.5		4	Nm
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	13.0	9.7			mm
$d_{Spb/Apb}$			*terminal to backside*	16.0	16.0			mm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; I_{ISOL} ≤ 1 mA		3600			V
		t = 1 minute			3000			V



Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MDD72-16N1B	MDD72-16N1B	Box	6	453218

Equivalent Circuits for Simulation

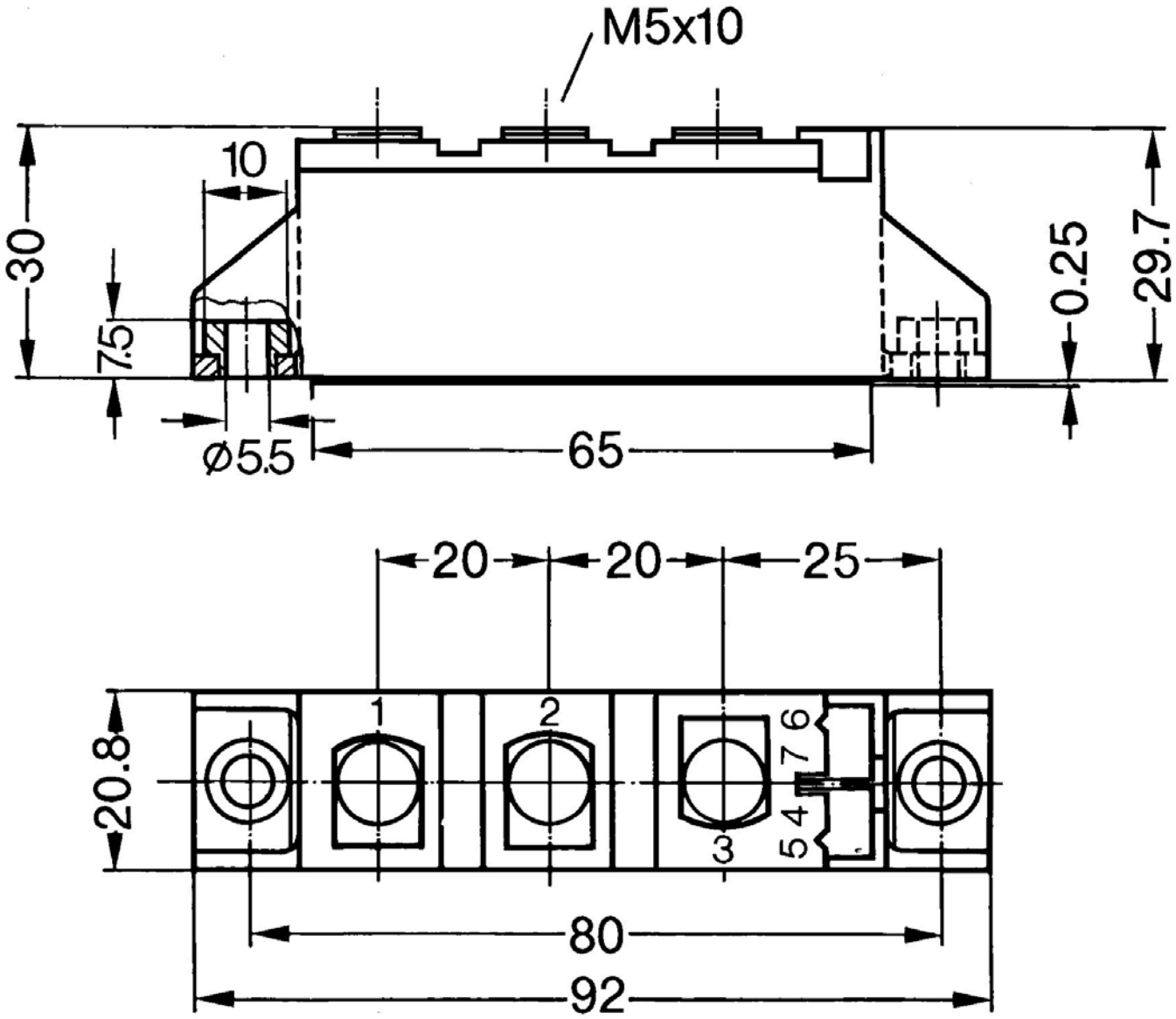
** on die level* T_{VJ} = 150 °C

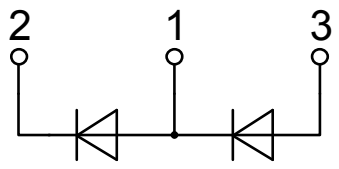


Rectifier

$V_{0\,max}$	*threshold voltage*	0.8	V
$R_{0\,max}$	*slope resistance **	1.1	mΩ

Outlines TO-240AA





Rectifier

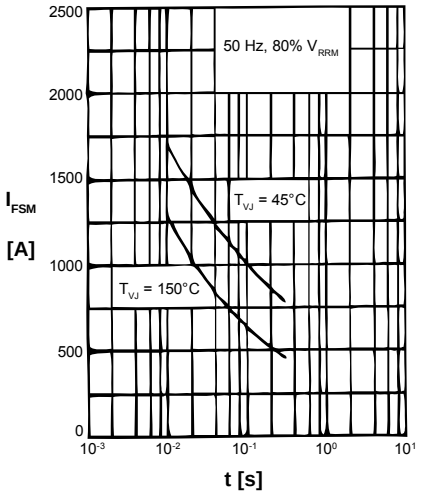


Fig. 1 Surge overload current
I_{TSM}, I_{FSM}: Crest value, t: duration

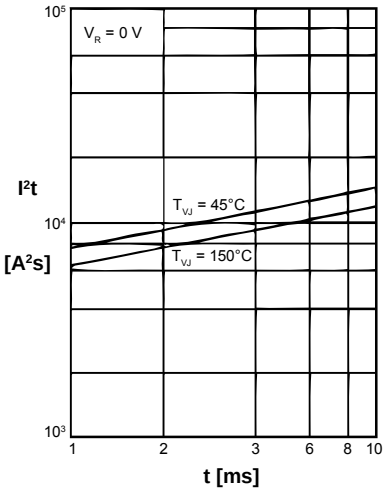


Fig. 2 I^2t versus time (1-10 ms)

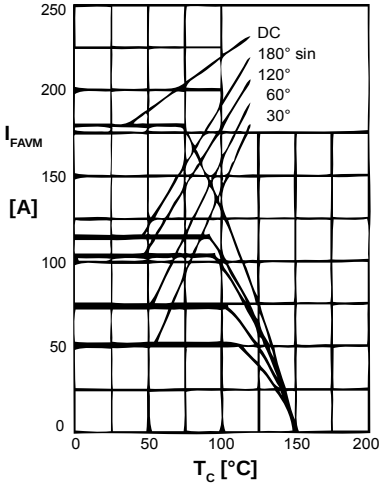


Fig. 3 Maximum forward current at case temperature

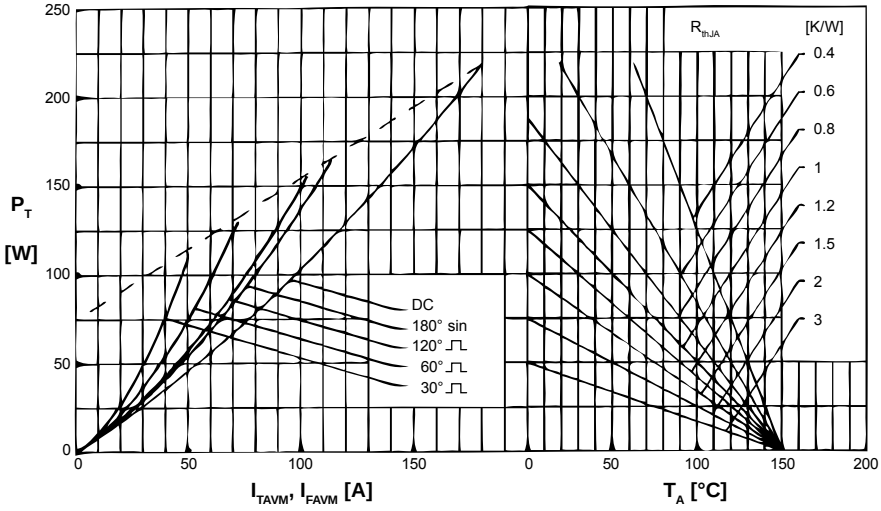


Fig. 4 Power dissipation vs. onstate current and ambient temperature (per diode)

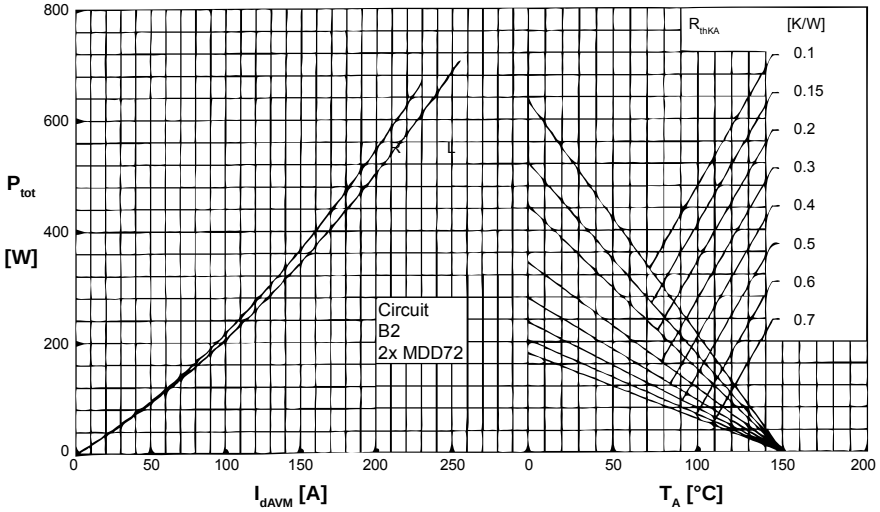


Fig. 6 Single phase rectifier bridge: Power dissipation versus direct output current and ambient temperature; R = resistive load,L = inductive load

Rectifier

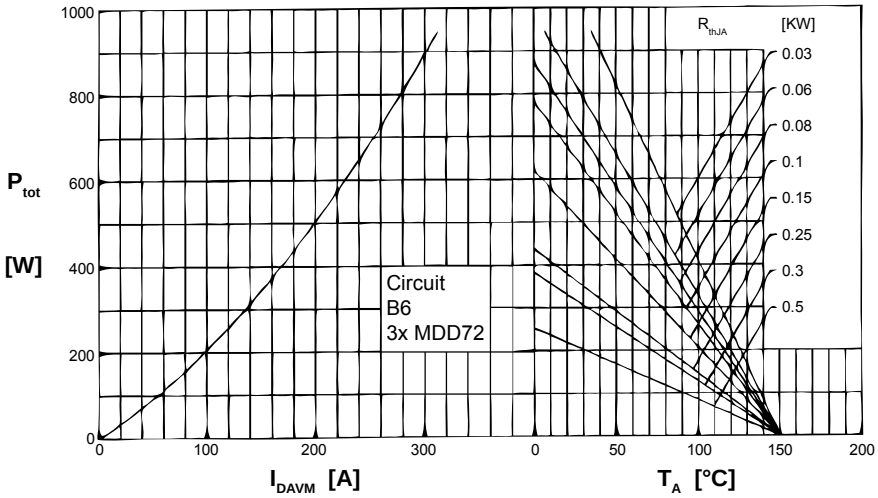


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

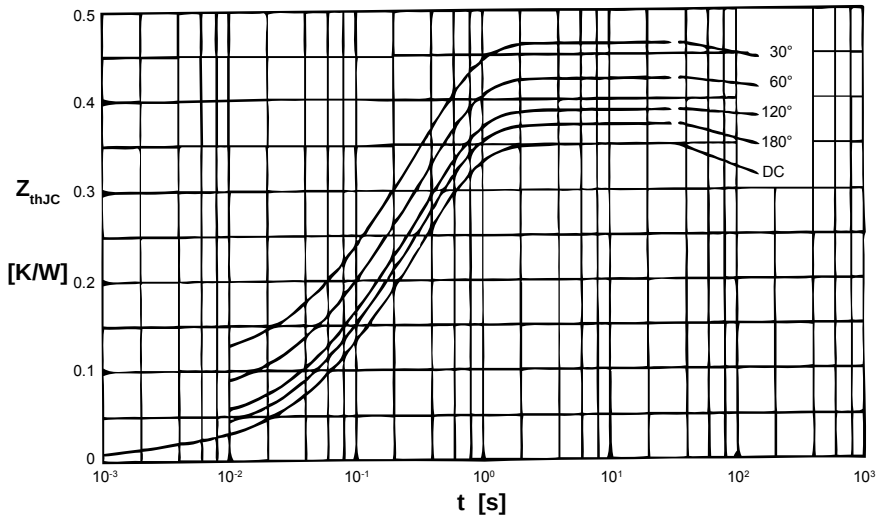


Fig. 7 Transient thermal impedance junction to case (per diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} [K/W]
DC	0.35
180°	0.37
120°	0.39
60°	0.43
30°	0.47

Constants for Z_{thJC} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.013	0.0014
2	0.072	0.0620
3	0.265	0.3750

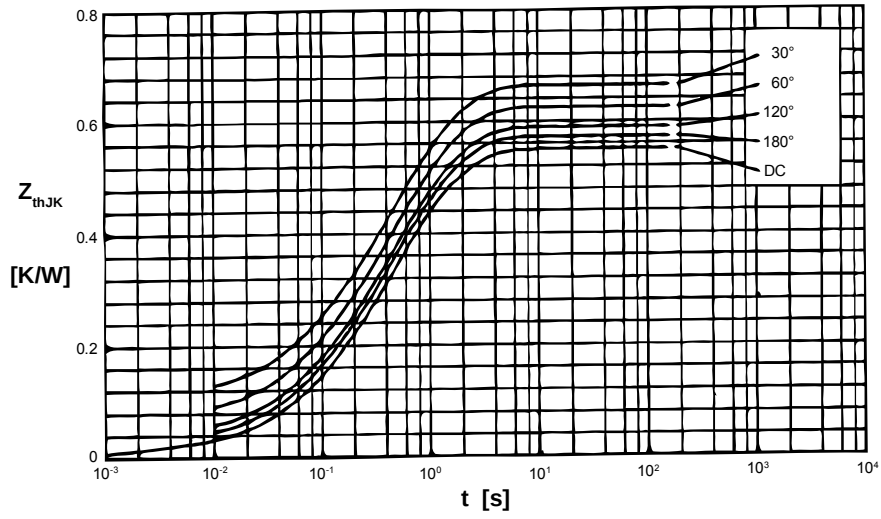


Fig. 8 Transient thermal impedance junction to heatsink (per thyristor)

R_{thJK} for various conduction angles d:

d	R_{thJK} [K/W]
DC	0.55
180°	0.57
120°	0.59
60°	0.63
30°	0.67

Constants for Z_{thJK} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.013	0.0014
2	0.072	0.0620
3	0.265	0.3750
4	0.200	1.3200